

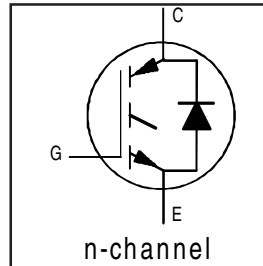
# IRG4BC10SD

INSULATED GATE BIPOLAR TRANSISTOR WITH  
ULTRAFAST SOFT RECOVERY DIODE

Standard Speed CoPack  
IGBT

### Features

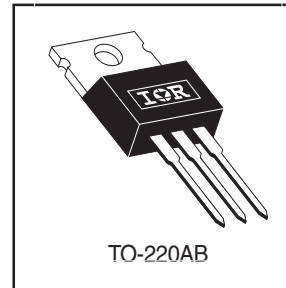
- Extremely low voltage drop 1.1Vtyp. @ 2A
- S-Series: Minimizes power dissipation at up to 3 KHz PWM frequency in inverter drives, up to 4 KHz in brushless DC drives.
- Very Tight Vce(on) distribution
- IGBT co-packaged with HEXFRED™ ultrafast, ultra-soft-recovery anti-parallel diodes for use in bridge configurations
- Industry standard TO-220AB package



|                                   |
|-----------------------------------|
| $V_{CES} = 600V$                  |
| $V_{CE(on)} \text{ typ.} = 1.10V$ |
| @ $V_{GE} = 15V, I_C = 2.0A$      |

### Benefits

- Generation 4 IGBTs offer highest efficiencies available
- IGBTs optimized for specific application conditions
- HEXFRED diodes optimized for performance with IGBTs . Minimized recovery characteristics require less/no snubbing
- Lower losses than MOSFET's conduction and Diode losses



### Absolute Maximum Ratings

|                           | Parameter                          | Max.                              | Units      |
|---------------------------|------------------------------------|-----------------------------------|------------|
| $V_{CES}$                 | Collector-to-Emitter Voltage       | 600                               | V          |
| $I_C @ T_C = 25^\circ C$  | Continuous Collector Current       | 14                                | A          |
| $I_C @ T_C = 100^\circ C$ | Continuous Collector Current       | 8.0                               |            |
| $I_{CM}$                  | Pulsed Collector Current ①         | 18                                |            |
| $I_{LM}$                  | Clamped Inductive Load Current ②   | 18                                |            |
| $I_F @ T_C = 100^\circ C$ | Diode Continuous Forward Current   | 4.0                               |            |
| $I_{FM}$                  | Diode Maximum Forward Current      | 18                                |            |
| $V_{GE}$                  | Gate-to-Emitter Voltage            | $\pm 20$                          | V          |
| $P_D @ T_C = 25^\circ C$  | Maximum Power Dissipation          | 38                                | W          |
| $P_D @ T_C = 100^\circ C$ | Maximum Power Dissipation          | 15                                |            |
| $T_J$                     | Operating Junction and             | -55 to +150                       | $^\circ C$ |
| $T_{STG}$                 | Storage Temperature Range          |                                   |            |
|                           | Soldering Temperature, for 10 sec. | 300 (0.063 in. (1.6mm) from case) |            |
|                           | Mounting Torque, 6-32 or M3 Screw. | 10 lbf•in (1.1 N•m)               |            |

### Thermal Resistance

|                 | Parameter                                 | Min. | Typ.      | Max. | Units        |
|-----------------|---|------|-----------|------|--------------|
| $R_{\theta JC}$ | Junction-to-Case - IGBT                   | —    | —         | 3.3  | $^\circ C/W$ |
| $R_{\theta JC}$ | Junction-to-Case - Diode                  | —    | —         | 7.0  |              |
| $R_{\theta CS}$ | Case-to-Sink, flat, greased surface       | —    | 0.50      | —    |              |
| $R_{\theta JA}$ | Junction-to-Ambient, typical socket mount | —    | —         | 80   |              |
| Wt              | Weight                                    | —    | 2.0(0.07) | —    | g (oz)       |

# IRG4BC10SD

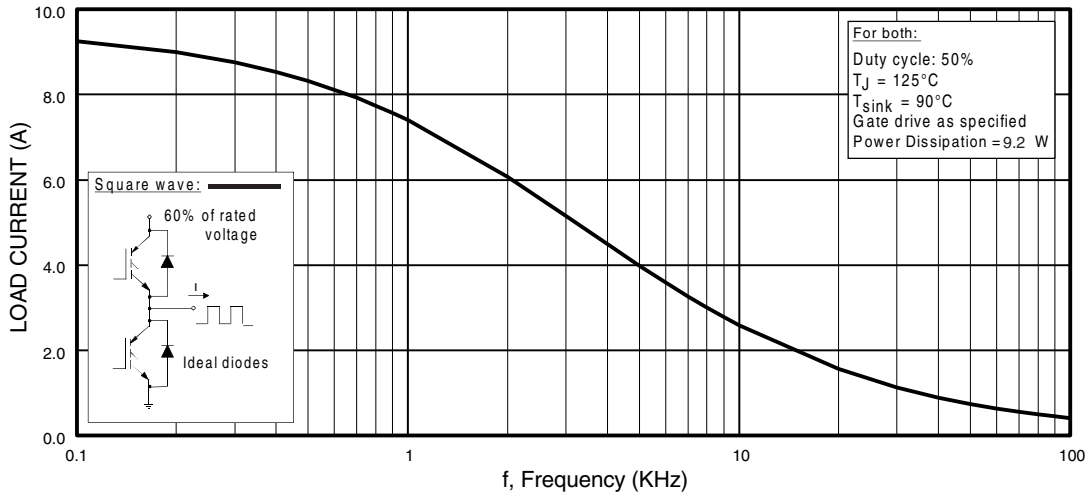
## Electrical Characteristics @ T<sub>J</sub> = 25°C (unless otherwise specified)

|  | Parameter   | Min. | Typ. | Max. | Units | Conditions   |
|--|---|------|------|------|-------|--|
| V <sub>(BR)CES</sub>                   | Collector-to-Emitter Breakdown Voltage <sup>③</sup> | 600  | —    | —    | V     | V <sub>GE</sub> = 0V, I <sub>C</sub> = 250μA   |
| ΔV <sub>(BR)CES</sub> /ΔT <sub>J</sub> | Temperature Coeff. of Breakdown Voltage             | —    | 0.64 | —    | V/°C  | V <sub>GE</sub> = 0V, I <sub>C</sub> = 1.0mA   |
| V <sub>CE(on)</sub>                    | Collector-to-Emitter Saturation Voltage             | —    | 1.58 | 1.7  | V     | I <sub>C</sub> = 8.0A<br>I <sub>C</sub> = 14.0A<br>I <sub>C</sub> = 8.0A, T <sub>J</sub> = 150°C                     |
|  |   | —    | 2.05 | —    |       |  |
|  |   | —    | 1.68 | —    |       |  |
| V <sub>GE(th)</sub>                    | Gate Threshold Voltage                              | 3.0  | —    | 6.0  |       | V <sub>CE</sub> = V <sub>GE</sub> , I <sub>C</sub> = 250μA   |
| ΔV <sub>GE(th)</sub> /ΔT <sub>J</sub>  | Temperature Coeff. of Threshold Voltage             | —    | -9.5 | —    | mV/°C | V <sub>CE</sub> = V <sub>GE</sub> , I <sub>C</sub> = 250μA   |
| g <sub>fe</sub>                        | Forward Transconductance <sup>④</sup>               | 3.65 | 5.48 | —    | S     | V <sub>CE</sub> = 100V, I <sub>C</sub> = 8.0A  |
| I <sub>CES</sub>                       | Zero Gate Voltage Collector Current                 | —    | —    | 250  | μA    | V <sub>GE</sub> = 0V, V <sub>CE</sub> = 600V<br>V <sub>GE</sub> = 0V, V <sub>CE</sub> = 600V, T <sub>J</sub> = 150°C |
|  |   | —    | —    | 1000 |       |  |
| V <sub>FM</sub>                        | Diode Forward Voltage Drop                          | —    | 1.5  | 1.8  | V     | I <sub>C</sub> = 4.0A<br>I <sub>C</sub> = 4.0A, T <sub>J</sub> = 150°C   |
|  |   | —    | 1.4  | 1.7  |       |  |
| I <sub>GES</sub>                       | Gate-to-Emitter Leakage Current                     | —    | —    | ±100 | nA    | V <sub>GE</sub> = ±20V   |

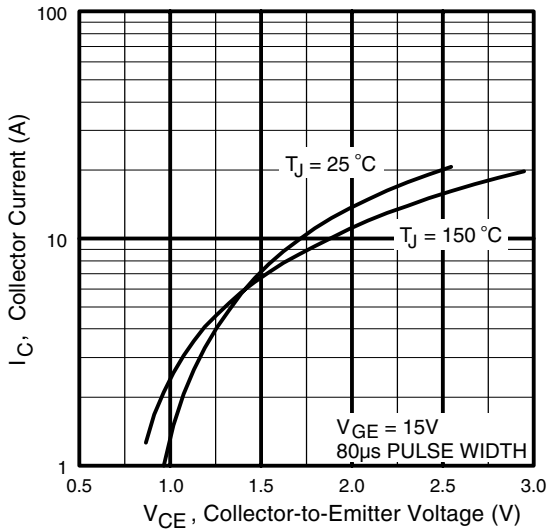
## Switching Characteristics @ T<sub>J</sub> = 25°C (unless otherwise specified)

|                          | Parameter   | Min. | Typ. | Max. | Units | Conditions   |
|--------------------------|---|------|------|------|-------|--|
| Q <sub>g</sub>           | Total Gate Charge (turn-on)                               | —    | 15   | 22   | nC    | I <sub>C</sub> = 8.0A<br>V <sub>CC</sub> = 400V<br>V <sub>GE</sub> = 15V<br>See Fig. 8   |
| Q <sub>ge</sub>          | Gate - Emitter Charge (turn-on)                           | —    | 2.42 | 3.6  |       |  |
| Q <sub>gc</sub>          | Gate - Collector Charge (turn-on)                         | —    | 6.53 | 9.8  |       |  |
| t <sub>d(on)</sub>       | Turn-On Delay Time  | —    | 76   | —    | ns    | T <sub>J</sub> = 25°C<br>I <sub>C</sub> = 8.0A, V <sub>CC</sub> = 480V<br>V <sub>GE</sub> = 15V, R <sub>G</sub> = 100Ω<br>Energy losses include "tail" and diode reverse recovery.<br>See Fig. 9, 10, 18 |
| t <sub>r</sub>           | Rise Time   | —    | 32   | —    |       |  |
| t <sub>d(off)</sub>      | Turn-Off Delay Time                                       | —    | 815  | 1200 |       |  |
| t <sub>f</sub>           | Fall Time   | —    | 720  | 1080 |       |  |
| E <sub>on</sub>          | Turn-On Switching Loss                                    | —    | 0.31 | —    |       |  |
| E <sub>off</sub>         | Turn-Off Switching Loss                                   | —    | 3.28 | —    | mJ    | See Fig. 9, 10, 18   |
| E <sub>ts</sub>          | Total Switching Loss                                      | —    | 3.60 | 10.9 |       |  |
| E <sub>ts</sub>          | Total Switching Loss                                      | —    | 1.46 | 2.6  | mJ    | I <sub>C</sub> = 5.0A  |
| t <sub>d(on)</sub>       | Turn-On Delay Time  | —    | 70   | —    | ns    | T <sub>J</sub> = 150°C, See Fig. 10,11, 18<br>I <sub>C</sub> = 8.0A, V <sub>CC</sub> = 480V<br>V <sub>GE</sub> = 15V, R <sub>G</sub> = 100Ω<br>Energy losses include "tail" and diode reverse recovery.  |
| t <sub>r</sub>           | Rise Time   | —    | 36   | —    |       |  |
| t <sub>d(off)</sub>      | Turn-Off Delay Time                                       | —    | 890  | —    |       |  |
| t <sub>f</sub>           | Fall Time   | —    | 890  | —    |       |  |
| E <sub>ts</sub>          | Total Switching Loss                                      | —    | 3.83 | —    | mJ    |  |
| L <sub>E</sub>           | Internal Emitter Inductance                               | —    | 7.5  | —    | nH    | Measured 5mm from package  |
| C <sub>ies</sub>         | Input Capacitance   | —    | 280  | —    | pF    | V <sub>GE</sub> = 0V<br>V <sub>CC</sub> = 30V<br>f = 1.0MHz<br>See Fig. 7  |
| C <sub>oes</sub>         | Output Capacitance  | —    | 30   | —    |       |  |
| C <sub>res</sub>         | Reverse Transfer Capacitance                              | —    | 4.0  | —    |       |  |
| t <sub>rr</sub>          | Diode Reverse Recovery Time                               | —    | 28   | 42   | ns    | T <sub>J</sub> = 25°C See Fig. 14  |
|                          |   | —    | 38   | 57   |       | T <sub>J</sub> = 125°C   |
| I <sub>rr</sub>          | Diode Peak Reverse Recovery Current                       | —    | 2.9  | 5.2  | A     | T <sub>J</sub> = 25°C See Fig. 15  |
|                          |   | —    | 3.7  | 6.7  |       | T <sub>J</sub> = 125°C   |
| Q <sub>rr</sub>          | Diode Reverse Recovery Charge                             | —    | 40   | 60   | nC    | T <sub>J</sub> = 25°C See Fig. 16  |
|                          |   | —    | 70   | 105  |       | T <sub>J</sub> = 125°C   |
| di <sub>(rec)</sub> M/dt | Diode Peak Rate of Fall of Recovery During t <sub>b</sub> | —    | 280  | —    | A/μs  | T <sub>J</sub> = 25°C See Fig. 17  |
|                          |   | —    | 235  | —    |       | T <sub>J</sub> = 125°C   |

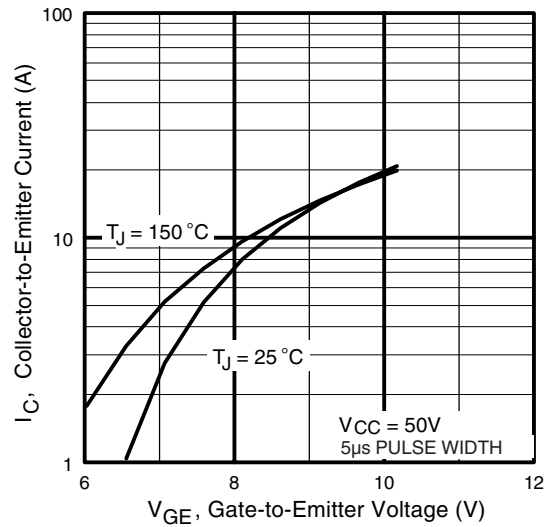
Details of note ① through ④ are on the last page



**Fig. 1 - Typical Load Current vs. Frequency**  
 (Load Current =  $I_{\text{RMS}}$  of fundamental)

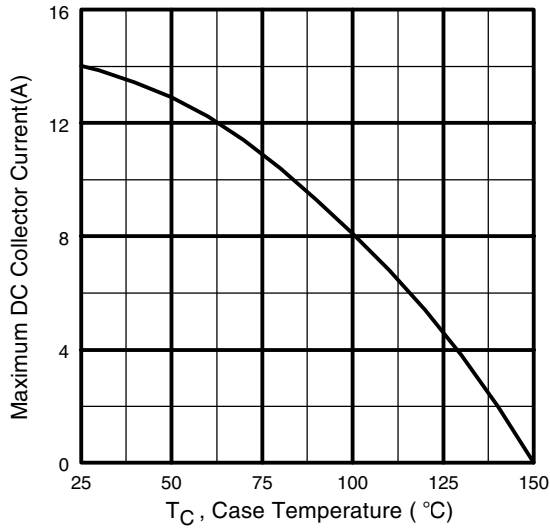


**Fig. 2 - Typical Output Characteristics**

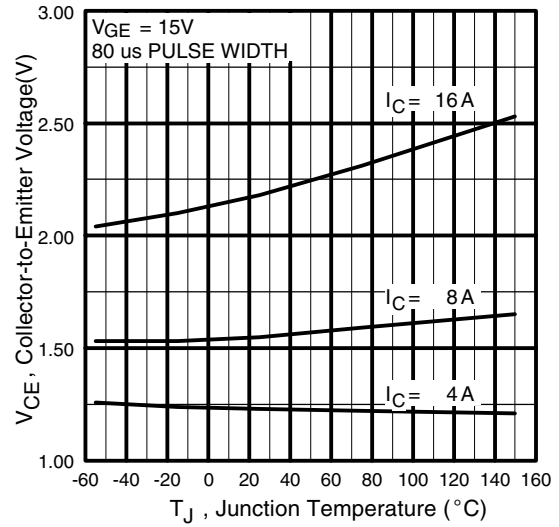


**Fig. 3 - Typical Transfer Characteristics**

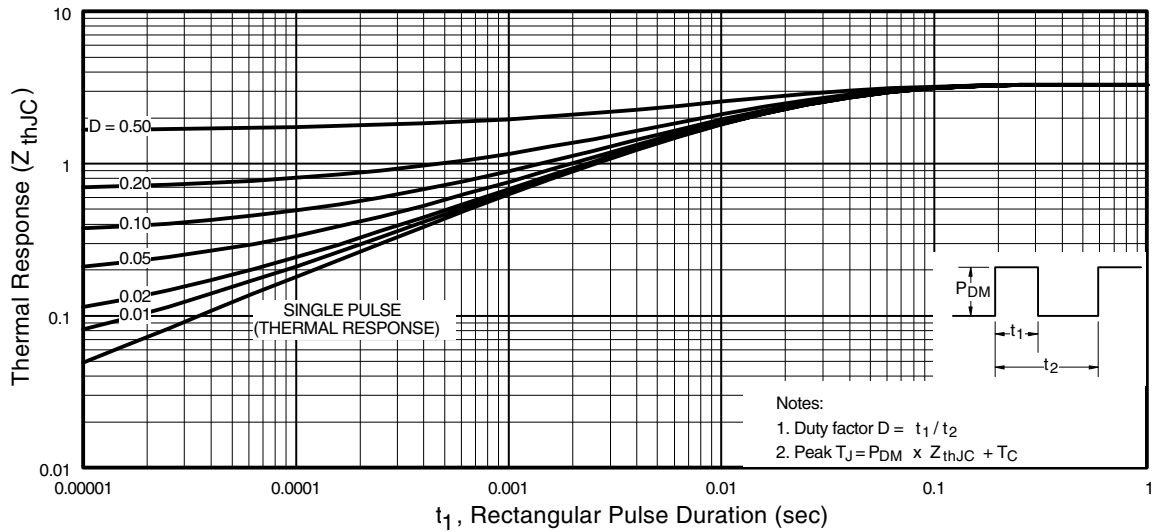
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**Fig. 4** - Maximum Collector Current vs. Case Temperature

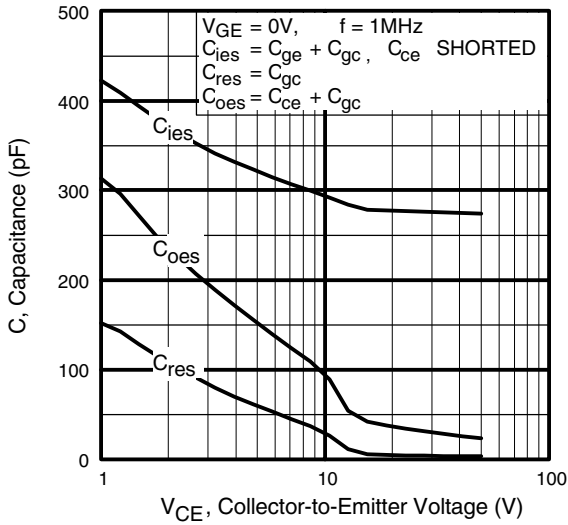


**Fig. 5** - Typical Collector-to-Emitter Voltage vs. Junction Temperature

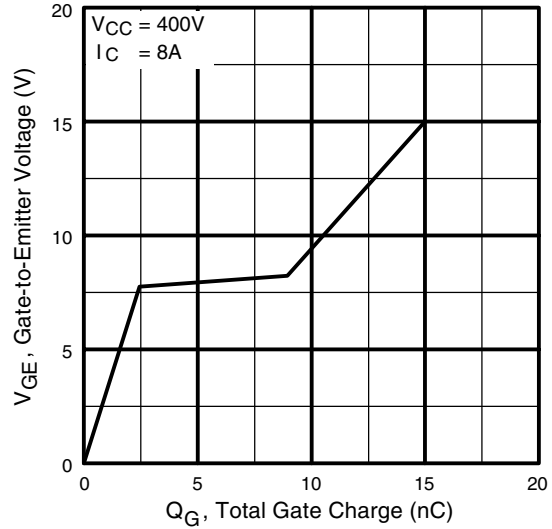


**Fig. 6** - Maximum Effective Transient Thermal Impedance, Junction-to-Case

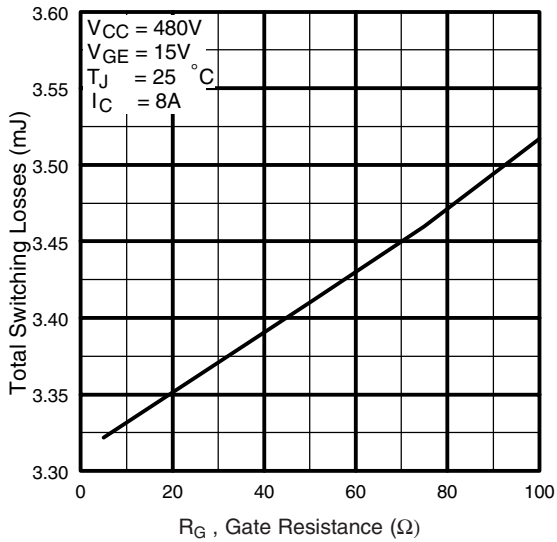
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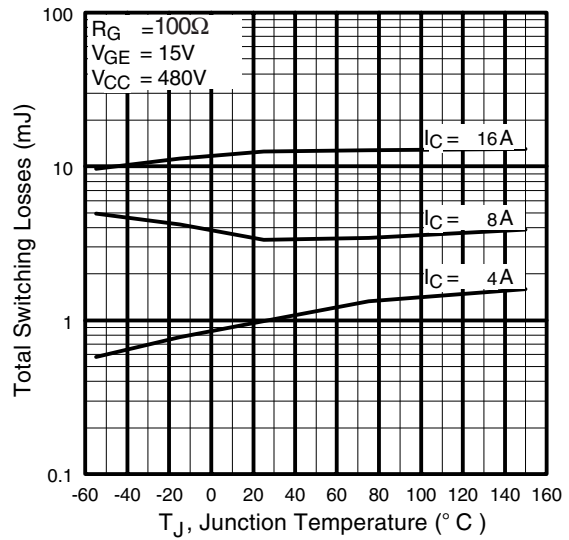
**Fig. 7** - Typical Capacitance vs. Collector-to-Emitter Voltage



**Fig. 8** - Typical Gate Charge vs. Gate-to-Emitter Voltage

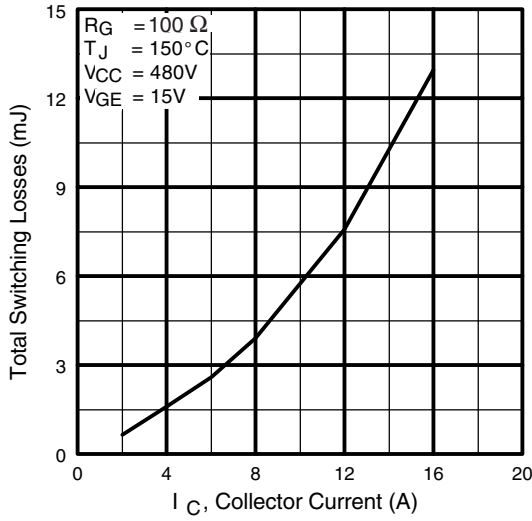


**Fig. 9** - Typical Switching Losses vs. Gate Resistance

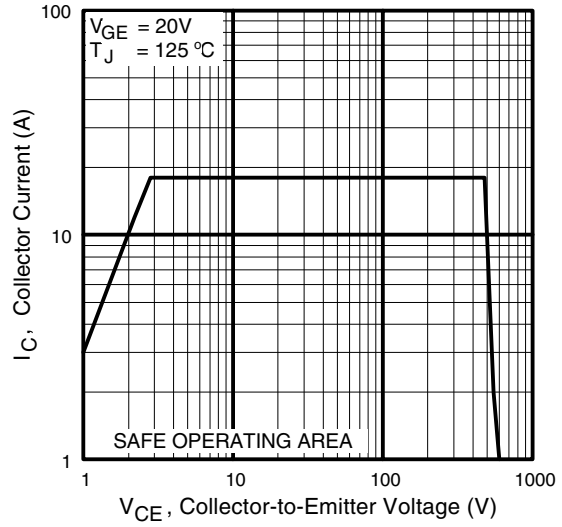


**Fig. 10** - Typical Switching Losses vs. Junction Temperature

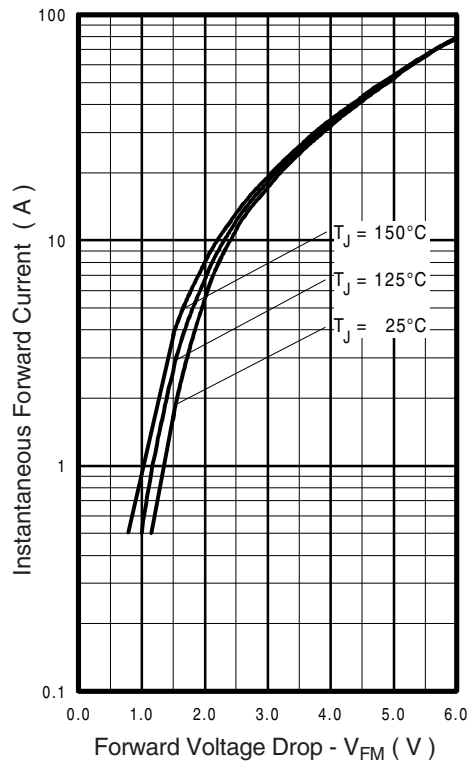
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**Fig. 11** - Typical Switching Losses vs. Collector Current



**Fig. 12** - Turn-Off SOA



**Fig. 13** - Maximum Forward Voltage Drop vs. Instantaneous Forward Current

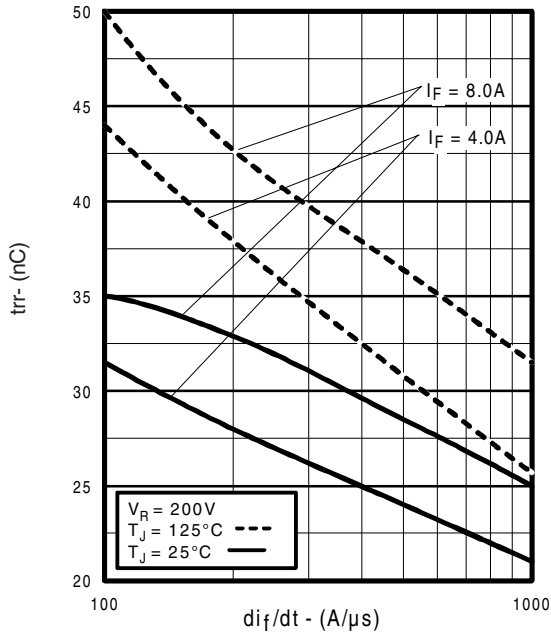


Fig. 14 - Typical Reverse Recovery vs.  $di_f/dt$

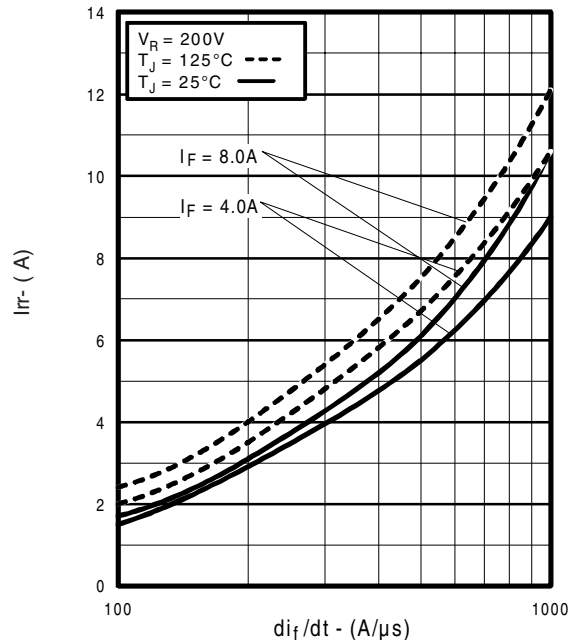


Fig. 15 - Typical Recovery Current vs.  $di_f/dt$

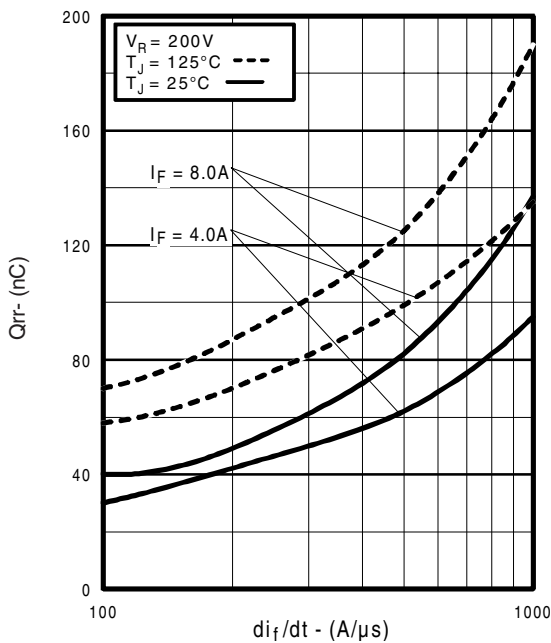


Fig. 16 - Typical Stored Charge vs.  $di_f/dt$

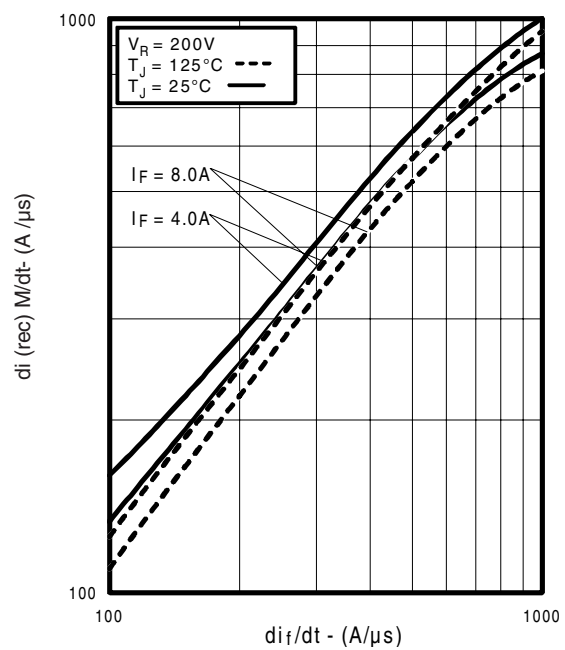
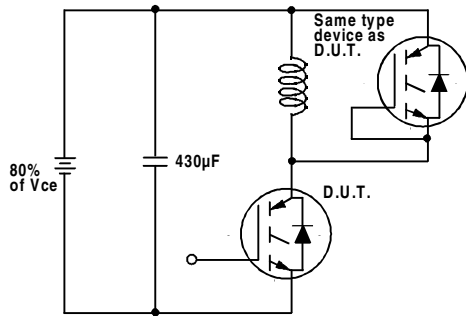
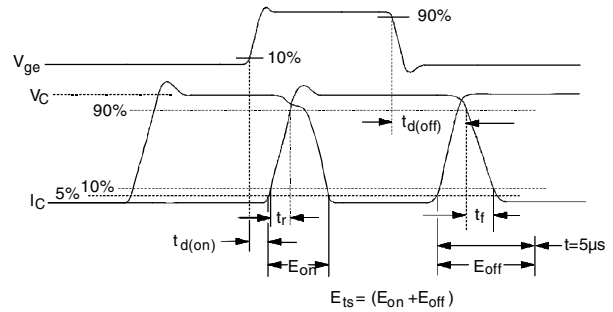


Fig. 17 - Typical  $di_{(rec)M}/dt$  vs.  $di_f/dt$

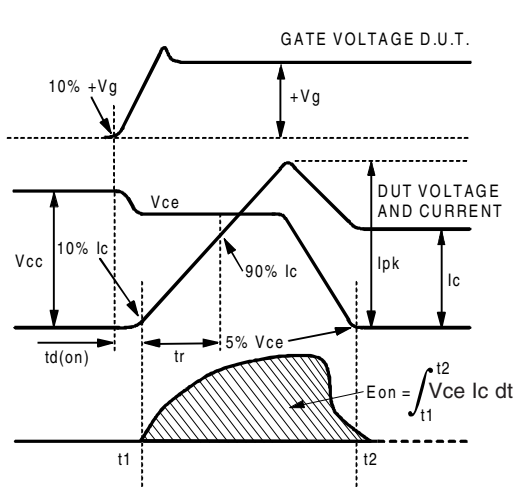
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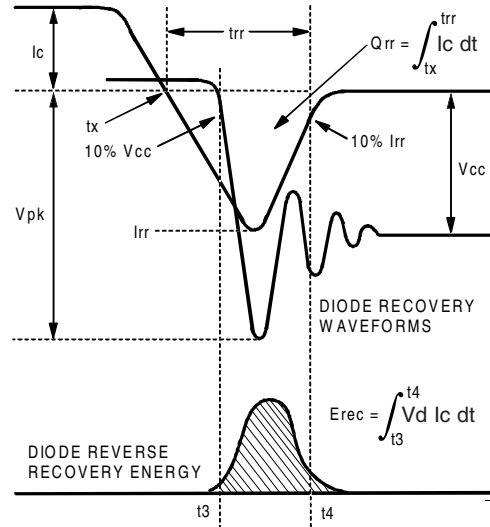
**Fig. 18a** - Test Circuit for Measurement of  $I_{LM}$ ,  $E_{on}$ ,  $E_{off}(\text{diode})$ ,  $t_{rr}$ ,  $Q_{rr}$ ,  $I_{rr}$ ,  $t_{d(on)}$ ,  $t_r$ ,  $t_{d(off)}$ ,  $t_f$



**Fig. 18b** - Test Waveforms for Circuit of Fig. 18a, Defining  $E_{off}$ ,  $t_{d(off)}$ ,  $t_f$



**Fig. 18c** - Test Waveforms for Circuit of Fig. 18a, Defining  $E_{on}$ ,  $t_{d(on)}$ ,  $t_r$



**Fig. 18d** - Test Waveforms for Circuit of Fig. 18a, Defining  $E_{rec}$ ,  $t_{rr}$ ,  $Q_{rr}$ ,  $I_{rr}$

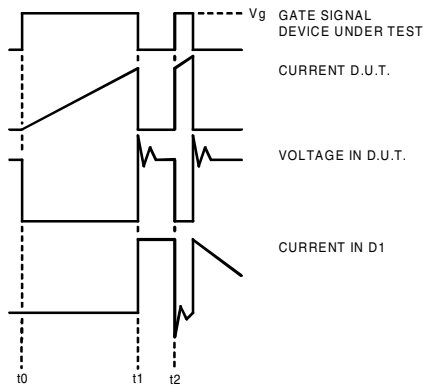


Figure 18e. Macro Waveforms for Figure 18a's Test Circuit

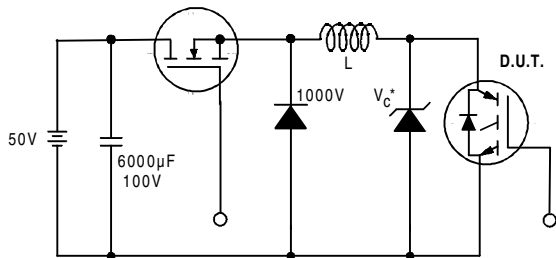


Figure 19. Clamped Inductive Load Test Circuit

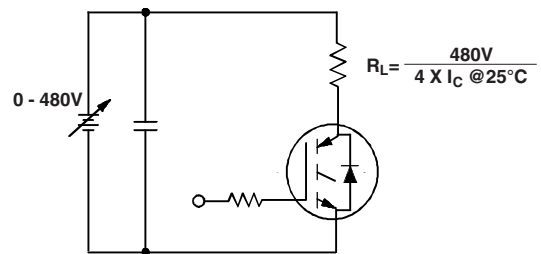


Figure 20. Pulsed Collector Current Test Circuit

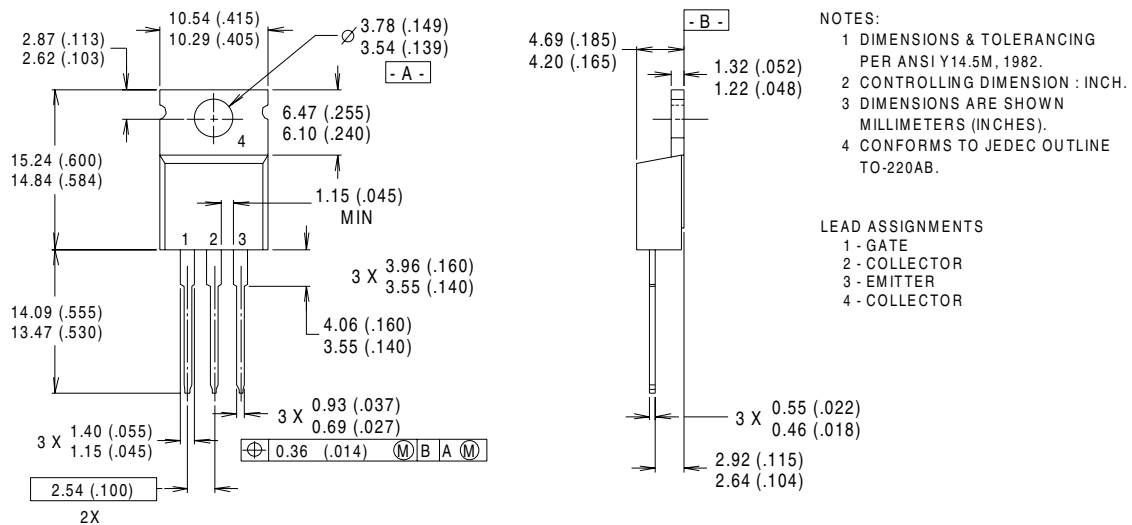
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International  
**IR** Rectifier

## Notes:

- ① Repetitive rating:  $V_{GE}=20V$ ; pulse width limited by maximum junction temperature (figure 20)
- ②  $V_{CC}=80\%(V_{CES})$ ,  $V_{GE}=20V$ ,  $L=10\mu H$ ,  $R_G = 100W$  (figure 19)
- ③ Pulse width  $\leq 80\mu s$ ; duty factor  $\leq 0.1\%$ .
- ④ Pulse width 5.0 $\mu s$ , single shot.

## Case Outline — TO-220AB



**CONFORMS TO JEDEC OUTLINE TO-220AB**

Dimensions in Millimeters and (Inches)

International  
**IR** Rectifier

**IR WORLD HEADQUARTERS:** 233 Kansas St., El Segundo, California 90245, USA Tel: (310) 252-7105

**IR EUROPEAN REGIONAL CENTRE:** 439/445 Godstone Rd, Whyteleafe, Surrey CR3 OBL, UK Tel: ++ 44 (0)20 8645 8000

**IR CANADA:** 15 Lincoln Court, Brampton, Ontario L6T3Z2, Tel: (905) 453 2200

**IR GERMANY:** Saalburgstrasse 157, 61350 Bad Homburg Tel: ++ 49 (0) 6172 96590

**IR ITALY:** Via Liguria 49, 10071 Borgaro, Torino Tel: ++ 39 011 451 0111

**IR JAPAN:** K&H Bldg., 2F, 30-4 Nishi-Ikebukuro 3-Chome, Toshima-Ku, Tokyo 171 Tel: 81 (0)3 3983 0086

**IR SOUTHEAST ASIA:** 1 Kim Seng Promenade, Great World City West Tower, 13-11, Singapore 237994 Tel: ++ 65 (0)838 4630

**IR TAIWAN:** 16 Fl. Suite D. 207, Sec. 2, Tun Haw South Road, Taipei, 10673 Tel: 886-(0)2 2377 9936

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